



- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

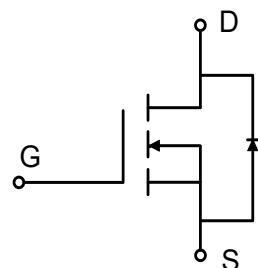
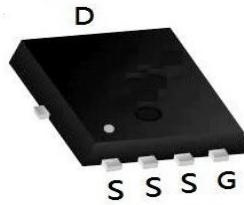
BVDSS	RDS(ON)	ID
200V	57 mΩ	30A

PDFN5060-8L Pin Configuration

Description

The XXW30N20F is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The XXW30N20F meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.



Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise specified):

Symbol	Parameter		Rating	Unit
Common Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)				
V_{DSS}	Drain-Source Voltage		200	V
V_{GSS}	Gate-Source Voltage		± 20	V
T_J	Maximum Junction Temperature		-55 to 175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55 to 175	$^\circ\text{C}$
I_S	Source Current-Continuous(Body Diode)	$T_C = 25^\circ\text{C}$	30	A
Mounted on Large Heat Sink				
I_{DM}	Pulsed Drain Current *	$T_C = 25^\circ\text{C}$	120	A
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	30	A
		$T_C = 100^\circ\text{C}$	20	A
P_D	Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	125	W
		$T_C = 100^\circ\text{C}$	62.5	W
R_{JJC}	Thermal Resistance, Junction-to-Case		1.2	$^\circ\text{C}/\text{W}$
R_{JJA}	Thermal Resistance, Junction-to-Ambient **		50	$^\circ\text{C}/\text{W}$
E_{AS}	Single Pulsed-Avalanche Energy ***	$L = 0.5\text{mH}$	161.8	mJ

Electrical Characteristics ($T_c = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HY1920			Unit
			Min	Typ.	Max	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=250\mu\text{A}$	200	-	-	V
I_{DSS}	Drain-to-Source Leakage Current	$V_{\text{DS}}=200\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
		$T_J=55^\circ\text{C}$	-	-	50	μA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=250\mu\text{A}$	3.0	3.7	5.0	V
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
$R_{\text{DS}(\text{ON})^*}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{DS}}=45\text{A}$		57	72	$\text{m}\Omega$
Diode Characteristics						
V_{SD}^*	Diode Forward Voltage	$I_{\text{SD}}=45\text{A}, V_{\text{GS}}=0\text{V}$	-	0.84	1.3	V
t_{rr}	Reverse Recovery Time	$I_{\text{SD}}=45\text{A}, dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$	-	97.7	-	ns
Q_{rr}	Reverse Recovery Charge		-	424.7	-	nC

Electrical Characteristics (Cont.) ($T_c = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HY1920			Unit
			Min	Typ.	Max	
Dynamic Characteristics						
R_G	Gate Resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	3.5	-	Ω
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, \text{Frequency}=1.0\text{MHz}$	-	2570	-	pF
C_{oss}	Output Capacitance		-	199	-	
C_{rss}	Reverse Transfer Capacitance		-	97	-	
$t_{\text{d}(\text{ON})}$	Turn-on Delay Time		-	15.18	-	
T_r	Turn-on Rise Time	$V_{\text{DD}}=100\text{V}, R_G=4\Omega, I_{\text{DS}}=45\text{A}, V_{\text{GS}}=10\text{V}$	-	39.7	-	ns
$t_{\text{d}(\text{OFF})}$	Turn-off Delay Time		-	33.4	-	
T_f	Turn-off Fall Time		-	35.3	-	
Gate Charge Characteristics						
Q_g	Total Gate Charge	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=30\text{A}$	-	53	-	nC
Q_{gs}	Gate-Source Charge		-	15	-	
Q_{gd}	Gate-Drain Charge		-	19	-	

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

Typical Operating Characteristic

Figure 1: Power Dissipation

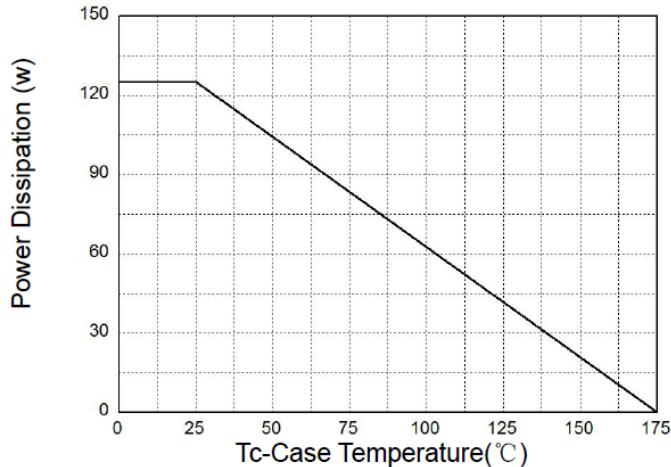


Figure 2: Drain Current

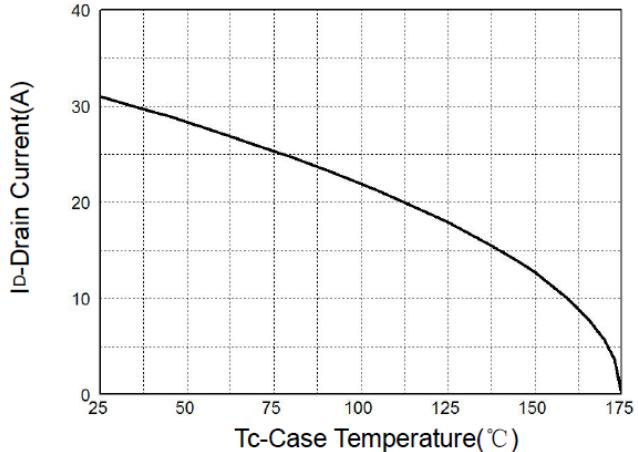


Figure 3: Safe Operation Area

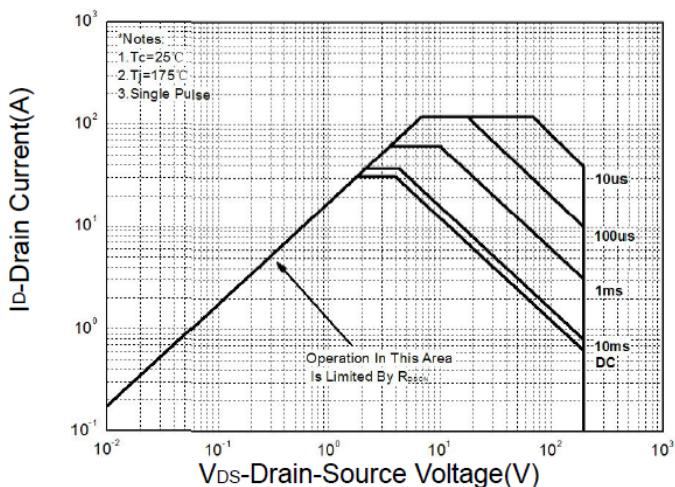


Figure 4: Thermal Transient Impedance

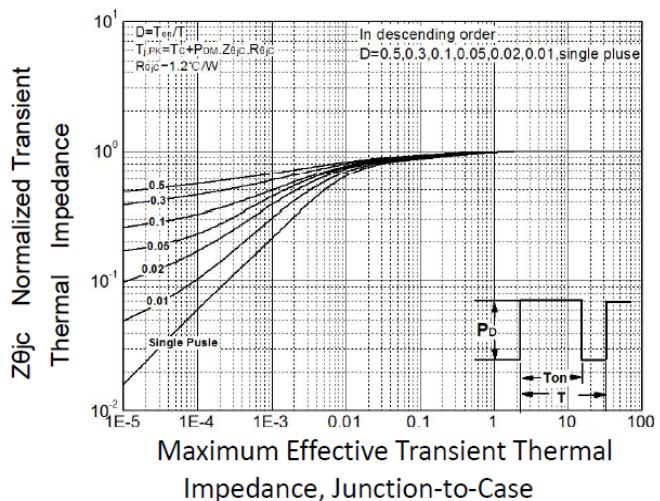


Figure 5: Output Characteristics

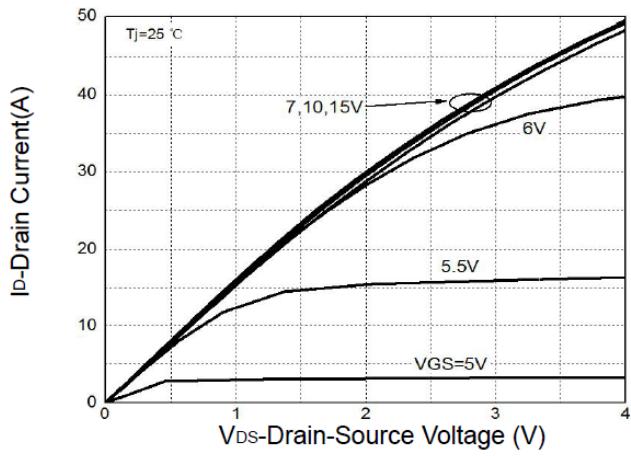
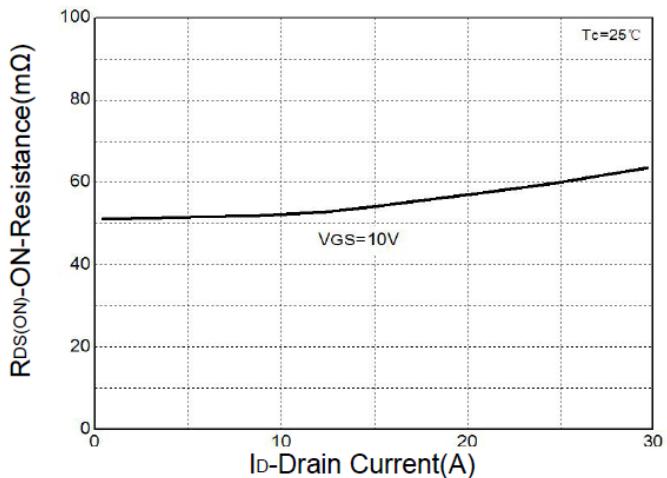


Figure 6: Drain-Source On Resistance



Typical Operating Characteristics(Cont.)

Figure 7: On-Resistance vs. Temperature

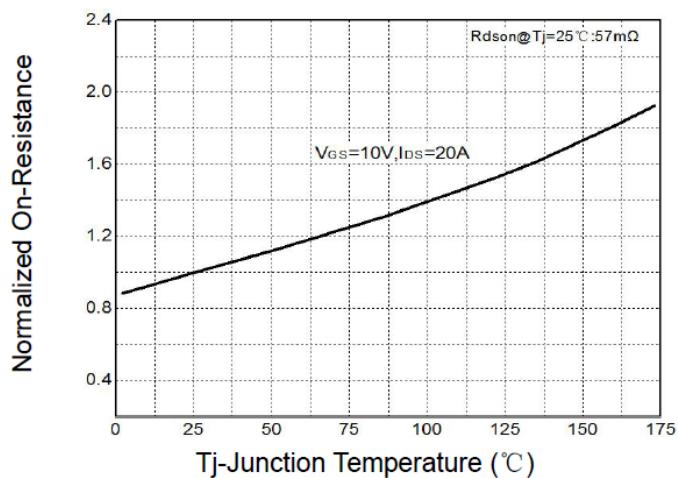


Figure 8: Source-Drain Diode Forward

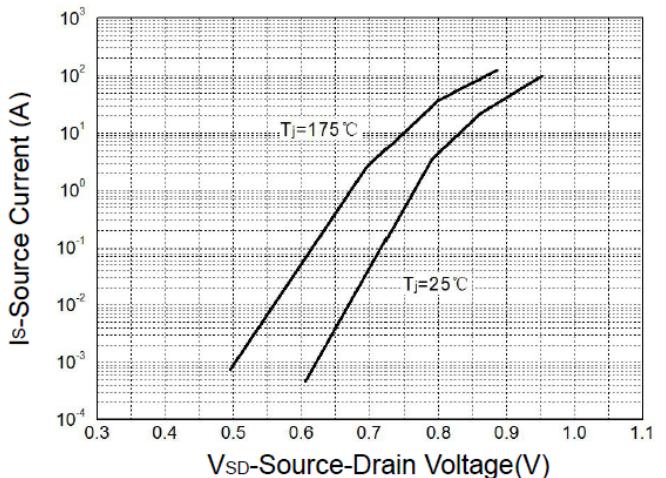


Figure 9: Capacitance Characteristics

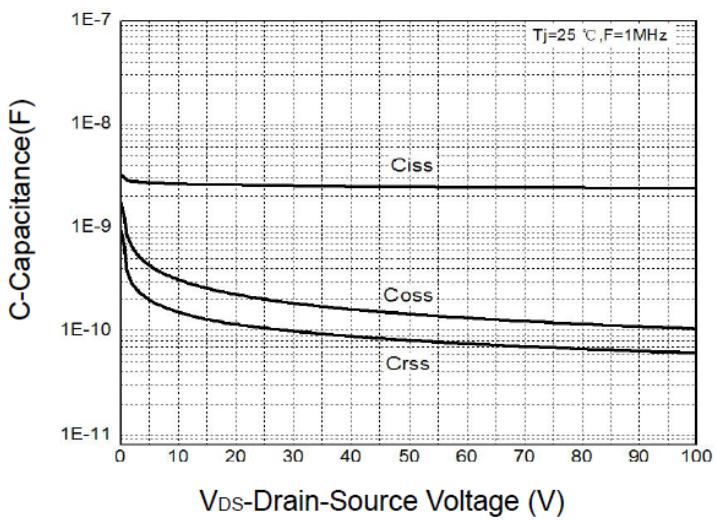
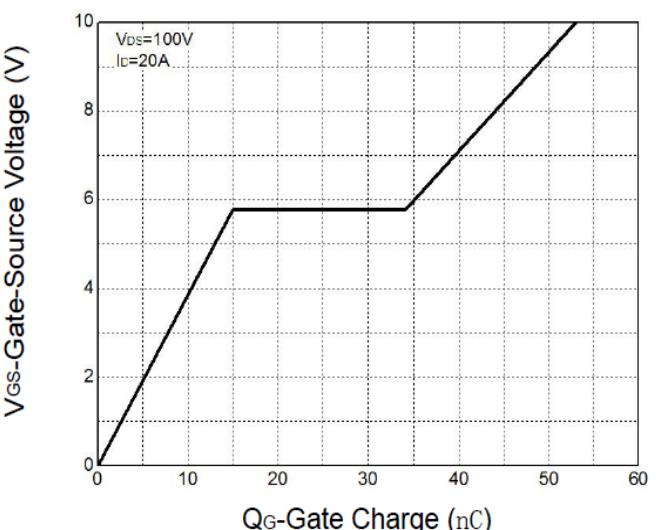
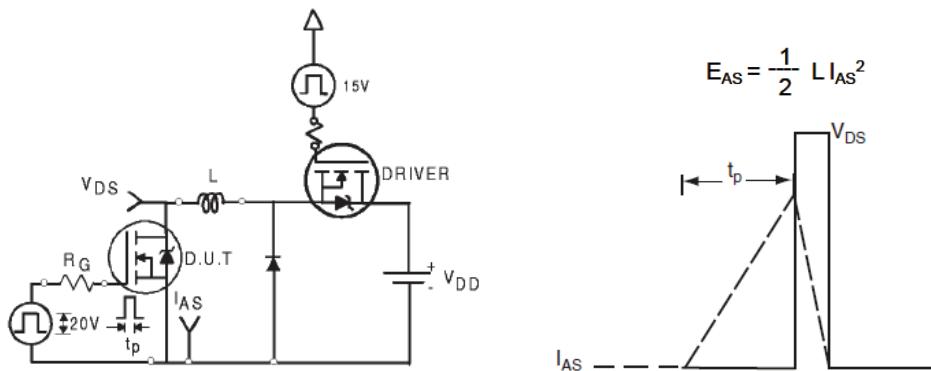


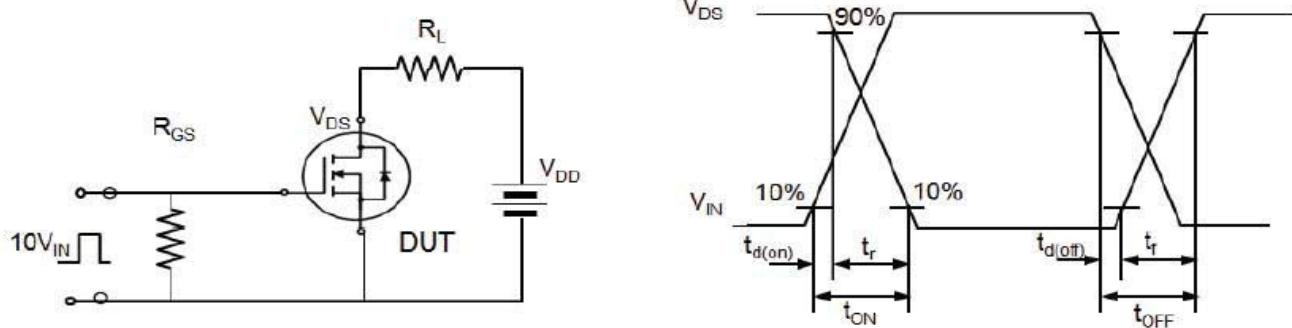
Figure 10: Gate Charge Characteristics



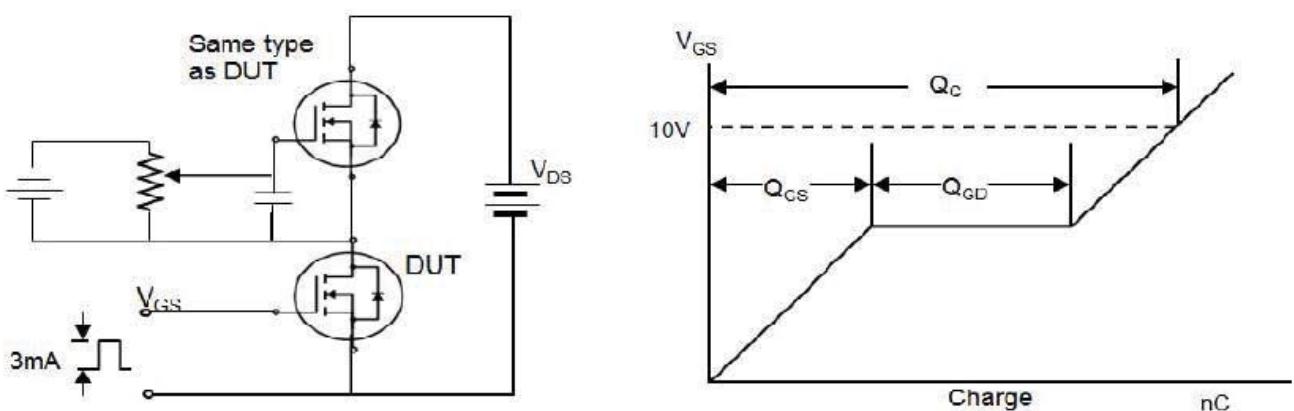
Avalanche Test Circuit

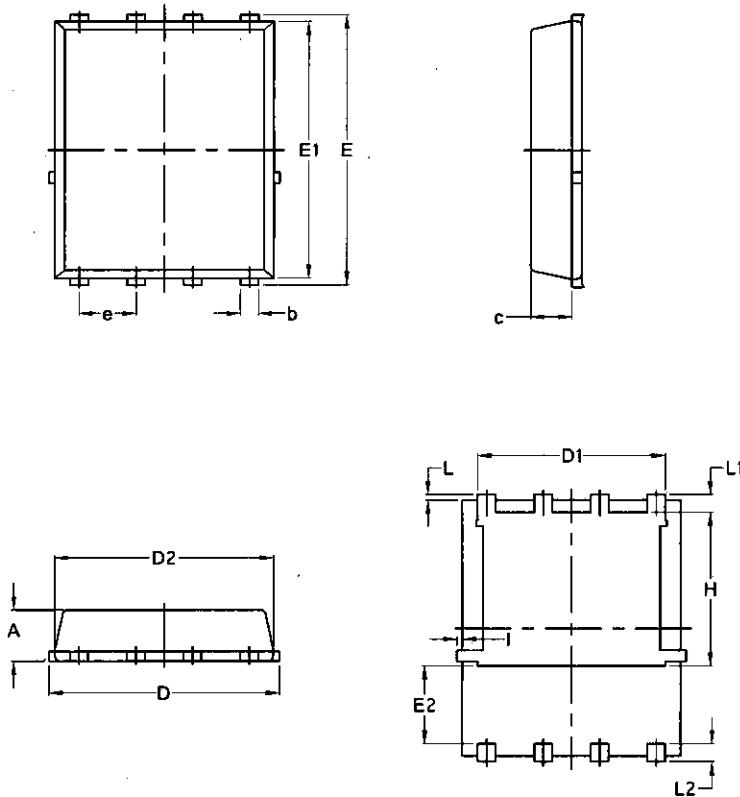


Switching Time Test Circuit



Gate Charge Test Circuit



Package Mechanical Data-PDFN5060-8L-JQ Single


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070